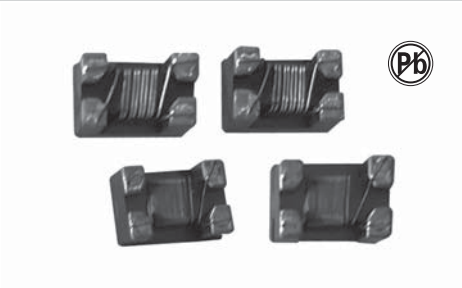
COMMON MODE CHOKES FASF2012,3216 SERIES



FEATURES:

Low profile and very small size SMD Design, Wound Chip constructure with standard 201212 to 482822 size,with best EMI suppression effect but least impact to data signal wave form.

APPLICATIONS:

Preventive measure against high speed signal radiation emissions such as USB 2.0 IEEE1394 or LAN interface. Best for NB, DSC, mobile device design.

GENERAL SPECIFICATIONS:

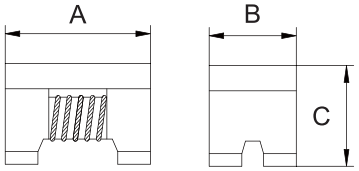
Impedance tolerance: Min at 20℃.
Operating temperature: -20℃ to +105℃.
Storage Temp: -0℃ to +40℃.
Resistance to Soldering Heat: 260℃ for 10 sec.
Temperature Rise: 40℃ Typ. at Rated Current.
All parts meet ROHS compliance.

ELECTRICAL CHARACTERISTICS

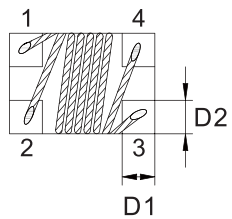
Part Number	Impedance (Ω)±25% 100MHz	D.C.Resistor (Ω) Max at 20°C	Rated current (mA)Max
FASF2012-120	12	0.20	450
FASF2012-240	24	0.25	420
FASF2012-320	32	0.25	400
FASF2012-500	50	0.25	400
FASF2012-670	67	0.25	400
FASF2012-750	75	0.70	280
FASF2012-900	90	0.30	400
FASF2012-121	120	0.30	370
FASF2012-141	140	0.32	360
FASF2012-161	160	0.35	350
FASF2012-181	180	0.35	330
FASF2012-201	200	0.40	300
FASF2012-221	220	0.40	300
FASF2012-261	260	0.40	300
FASF2012-371	370	0.45	280

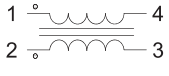
Part Number	Impedance (Ω)±25% 100MHz	D.C.Resistor (Ω) Max at 20°C	Rated current (mA)Max
FASF3216-330	33	0.20	400
FASF3216-500	50	0.25	400
FASF3216-900	90	0.30	400
FASF3216-121	120	0.30	400
FASF3216-161	160	0.40	350
FASF3216-221	220	0.45	300
FASF3216-261	260	0.50	300
FASF3216-501	500	0.80	260
FASF3216-601	600	0.80	260
FASF3216-102	1000	1.00	250
FASF3216-222	2200	1.20	200

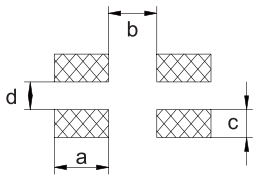
TECHNICAL INFORMATION



ELECTRICAL SCHEMATIC & PAD LAYOUT







DIMENSIONS: MM

Part number	A	B	C	D1	D2	a	b	c	d
FASF2012	2.00±0.2	1.20±0.2	1.20±0.2	0.45 REF	0.40 REF	0.90 REF	0.80 REF	0.40 REF	0.40 REF
FASF3216	3.20±0.2	1.60±0.2	2.00±0.2	0.60 REF	0.60 REF	1.05 REF	1.60 REF	0.60 REF	0.40 REF